

| L Number | Hits  | Search Text  | DB  | Time stamp       |
|----------|-------|--|---|------------------|
| 14       | 671   | (257/697).CCLS.  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2002/09/09 15:37 |
| 16       | 812   | (257/696).CCLS.  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2002/09/09 15:37 |
| 20       | 1108  | (257/693).CCLS.  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2002/09/09 15:37 |
| 26       | 3120  | tape with lead with frame  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2002/09/09 15:38 |
| 28       | 883   | tape with ceramic with substrate                                       | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2002/09/09 15:38 |
| 32       | 37201 | chip with wire better with solder and<br>(257/\$).ccls.                | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2002/09/09 15:39 |
| 33       | 37101 | chip with wire better with solder with<br>cost and (257/\$).ccls.      | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2002/09/09 15:40 |
| 34       | 0     | chip with wire with better with solder<br>with cost and (257/\$).ccls. | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2002/09/09 15:40 |
| 35       | 0     | chip with wire with better with solder<br>and (257/\$).ccls.           | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2002/09/09 15:40 |
| 36       | 740   | chip with wire with solder and<br>(257/\$).ccls.                       | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2002/09/09 15:40 |
| 46       | 980   | lead with frame with use   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2002/09/09 15:42 |
| 48       | 593   | (361/813).CCLS.  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2002/09/09 15:42 |
| 49       | 269   | ((361/813).CCLS.) and lead adj frame                                   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2002/09/09 15:42 |
| 15       | 145   | ((257/697).CCLS.) and ceramic with<br>substrate                        | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2002/09/09 15:42 |

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| 17 | 59  | ((257/696).CCLS.) and ceramic with substrate  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2002/09/09 15:42 |
| 18 | 5   | ("3911475"   "4001655"   "4717948"   "4758875"   "4803543").PN.   | USPÄT   | 2002/09/09 15:42 |
| 19 | 6   | 5130780.URPN.   | USPAT   | 2002/09/09 15:42 |
| 21 | 160 | ((257/693).CCLS.) and ceramic with substrate  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2002/09/09 15:43 |
| 22 | 15  | ("4965653"   "5218234"   "5291062"   "5334857"   "5355283"   "5433822"   "5468999"   "5497032"   "5552635"   "5581122"   "5598036"   "5604379"   "5640047"   "5717252"   "5731630").PN. | USPÄT   | 2002/09/09 15:43 |
| 23 | 3   | ("5350947"   "5352926"   "5367435").PN.   | USPAT   | 2002/09/09 15:43 |
| 24 | 5   | 5731630.URPN.   | USPAT   | 2002/09/09 15:43 |
| 25 | 5   | 5731630.URPN.   | USPAT   | 2002/09/09 15:43 |
| 27 | 25  | tape with lead with frame with ceramic with substrate   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2002/09/09 15:43 |
| 29 | 145 | (tape with ceramic with substrate) and (257/\$).ccls.   | USPÄT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2002/09/09 15:43 |
| 30 | 62  | glass adj epoxy with ceramic and tape and lead and (257/\$).ccls.   | USPÄT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2002/09/09 15:43 |
| 31 | 17  | glass adj epoxy with ceramic with heat and (257/\$).ccls.   | USPÄT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2002/09/09 15:43 |
| 37 | 8   | chip with wire with solder with design and (257/\$).ccls.   | USPÄT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2002/09/09 15:43 |
| 38 | 5   | (wire with bond with solder with design and (257/\$).ccls.) not ( chip with wire with solder with design and (257/\$).ccls.)  | USPÄT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2002/09/09 15:43 |
| 39 | 8   | (wire with bond with solder with design and (257/\$).ccls.) not ((257/693).CCLS.)   | USPÄT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2002/09/09 15:43 |
| 40 | 8   | wire with bond with solder with design and (257/\$).ccls.   | USPÄT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2002/09/09 15:43 |
| 41 | 20  | Solder with wire with bumping and (257/\$).ccls.  | USPÄT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2002/09/09 15:43 |
| 42 | 5   | Solder with wire with integration and (257/\$).ccls.  | USPÄT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2002/09/09 15:43 |

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| 43 | 3   | 6339260.pn.  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM TDB | 2002/09/09 15:43 |
| 44 | 41  | wire with cost with solder and<br>(257/\$).ccls.           | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM TDB | 2002/09/09 15:43 |
| 45 | 2   | 6064116.pn.  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM TDB | 2002/09/09 15:43 |
| 47 | 171 | (lead with frame with use) and<br>(257/\$).ccls.           | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM TDB | 2002/09/09 15:43 |
| 50 | 70  | ((361/813).CCLS.) and lead adj frame) not<br>semiconductor | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM TDB | 2002/09/09 15:43 |